ABSTRACT

The probe card 100 includes a contactor 92, a substrate 94, a signal transmission path 96, a grounding conductor 98 and a hole 102. The signal transmission path 96 is formed on the substrate 94. The substrate 94 is made of a dielectric or semiconductor material. The contactor 92 is made of a metallic glass material on an end portion of the signal transmission path 96 on one side of the substrate 94. By using micromachining technology on the metallic glass materials, it is possible to form the contactor 92 to be extremely minute and also to form a plurality of the contactors 92 substantially simultaneously. The contactor 92 is formed to be away from the substrate 94 over the hole 102. The contactor 92 has elasticity in a vertical direction against the surface of the substrate 94, and, the contactor 92 can elastically contact to the contact terminal formed on the circuit under test during a test. Since the probe card 100 of the present invention has a contactor 92 made of a metallic glass material, it is possible to provide a probe card which can transmit high frequency signals to an integrated circuit having a plurality of pads on an area of a narrow pitch.



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